

Abstract

The invention relates to an apparatus and a method for applying semiconductor chips (5) to a plurality of substrates (4), in particular smartcard modules or flexboards, wherein at an adhesive application device (1) adhesive is applied to the substrate (4) at predefined substrate positions, at a fitting device (2) the substrate (4) is fitted with the semiconductor chips (5) at the substrate positions, and in a curing device (3) the adhesive is cured, wherein the curing device (3) and/or a further device can be connected by a clamping device (13, 14) to a conveyor belt (6) which transports the substrates (4) along the devices, and can be moved in the transport direction, at a transport speed of the conveyor belt (6), by a lifting device (15).

(Fig. 2)

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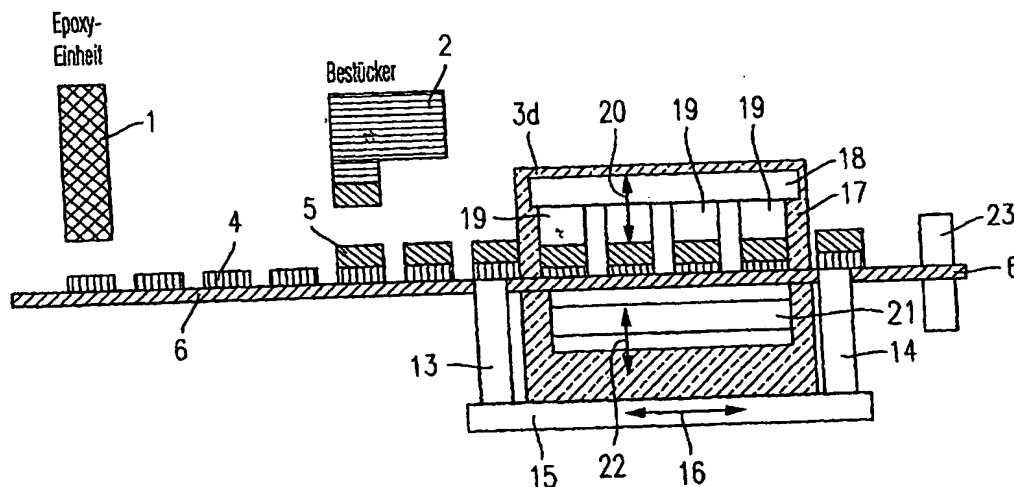
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[Fortsetzung auf der nächsten Seite]

(54) Title: DEVICE AND METHOD FOR APPLYING SEMICONDUCTOR CHIPS TO CARRIERS

(54) Bezeichnung: VORRICHTUNG UND VERFAHREN ZUR AUFBRINGUNG VON HALBLEITERCHIPS AUF TRÄGERN



1... EPOXY UNIT
2... FITTING DEVICE

(57) Abstract: The invention relates to a device and a method for applying semiconductor chips (5) to a plurality of carriers (4), especially smart card modules or flexboards. According to the invention, an adhesive application device (1) is used to apply an adhesive to pre-defined positions on the carrier (4), a fitting device (2) is used to apply the semiconductor chips (5) to the positions on the carrier (4), and a hardening device (3) is used to harden the adhesive. The hardening device (3) and/or another device can be connected to a conveyor belt (6) for transporting the carrier (4) along the devices, by means of a clamping device (13, 14), and can be displaced in the transport direction at the speed of the conveyor belt (6), by means of a lifting device (15).

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